

Single D-Type Flip-Flop With 3-State Output

Check for Samples: [SN74LVC1G374](#)

FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Provides Down Translation to V_{CC}
- Max t_{pd} of 4 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION

This single D-type latch is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G374 features a 3-state output designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, input/output (I/O) ports, bidirectional bus drivers, and working registers.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

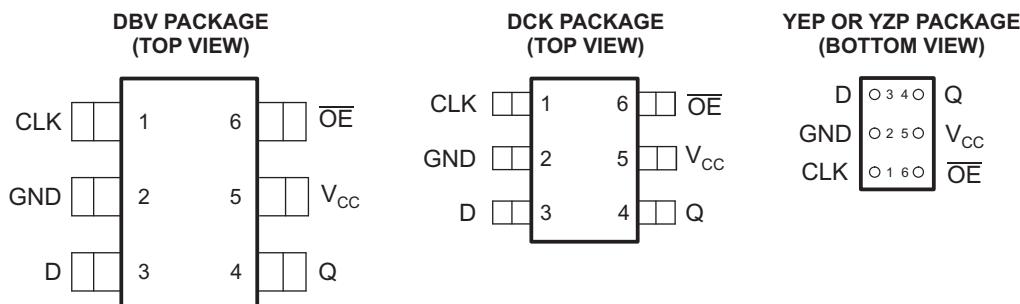
On the positive transition of the clock (CLK) input, the Q output is set to the logic level set up at the data (D) input.

A buffered output-enable (\overline{OE}) input can be used to place the output in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the output neither loads nor drives the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



See mechanical drawings for dimensions.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.
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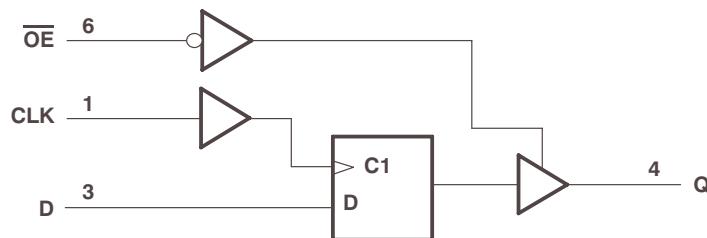


These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Function Table

INPUTS			OUTPUT
\overline{OE}	CLK	D	Q
L	↑	L	L
L	↑	H	H
L	H or L	X	Q
H	X	X	Z

Logic Diagram (Positive Logic)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V_{CC}	Supply voltage range	-0.5	6.5	V	
V_I	Input voltage range ⁽²⁾	-0.5	6.5	V	
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V	
V_O	Voltage range applied to any output in the high or low state ^{(2) (3)}	-0.5	$V_{CC} + 0.5$	V	
I_{IK}	Input clamp current	$V_I < 0$		-50 mA	
I_{OK}	Output clamp current	$V_O < 0$		-50 mA	
I_O	Continuous output current				± 50 mA
	Continuous current through V_{CC} or GND				± 100 mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DBV package		165	$^{\circ}\text{C}/\text{W}$
		DCK package		259	
		YEP/YZP package		123	
T_{stg}	Storage temperature range	-65	150	$^{\circ}\text{C}$	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 3 V to 3.6 V	2		
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 3 V to 3.6 V	0.8		
		V _{CC} = 4.5 V to 5.5 V	0.3 × V _{CC}		
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V		-4	mA
		V _{CC} = 2.3 V		-8	
		V _{CC} = 3 V		-16	
		V _{CC} = 4.5 V		-24	
				-32	
I _{OL}	Low-level output current	V _{CC} = 1.65 V		4	mA
		V _{CC} = 2.3 V		8	
		V _{CC} = 3 V		16	
		V _{CC} = 4.5 V		24	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	ns/V
		V _{CC} = 3.3 V ± 0.3 V		10	
		V _{CC} = 5 V ± 0.5 V		5	
T _A	Operating free-air temperature		-40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	–40°C to 85°C			–40°C to 125°C			UNIT	
			MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX		
V _{OH}	I _{OH} = –100 µA	1.65 V to 5.5 V	V _{CC} – 0.1			V _{CC} – 0.1			V	
	I _{OH} = –4 mA	1.65 V	1.2			1.2				
	I _{OH} = –8 mA	2.3 V	1.9			1.9				
	I _{OH} = –16 mA	3 V	2.4			2.4				
	I _{OH} = –24 mA		2.3			2.3				
	I _{OH} = –32 mA	4.5 V	3.8			3.8				
V _{OL}	I _{OL} = 100 µA	1.65 V to 5.5 V	0.1			0.1			V	
	I _{OL} = 4 mA	1.65 V	0.45			0.45				
	I _{OL} = 8 mA	2.3 V	0.3			0.3				
	I _{OL} = 16 mA	3 V	0.4			0.4				
	I _{OL} = 24 mA		0.55			0.65				
	I _{OL} = 32 mA	4.5 V	0.55			0.65				
I _I	V _I = 5.5 V or GND	0 to 5.5 V	±1			±2			µA	
I _{OZ}	V _O = 0 to 5.5 V		±5			±5			µA	
I _{off}	V _I or V _O = 5.5 V	0	±10			±10			µA	
I _{CC}	V _I = 5.5 V or GND, I _O = 0	1.65 V to 5.5 V	10			10			µA	
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V	500			500			µA	
C _i	V _I = V _{CC} or GND	3.3 V	3			3			pF	
C _o	V _O = V _{CC} or GND	3.3 V	6			6			pF	

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

		SN74LVC1G374 –40°C to 85°C								UNIT	
		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	Clock frequency	100		125		150		175		MHz	
t _w	Pulse duration, CLK high or low	3.3		3		2.8		2.5		ns	
t _{su}	Setup time, data before CLK ↑	3.5		2.5		2		1.5		ns	
t _h	Hold time, data after CLK ↑	3.4		1.6		1.5		1.5		ns	

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

		SN74LVC1G374 –40°C to 125°C								UNIT	
		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	Clock frequency	100		125		150		175		MHz	
t _w	Pulse duration, CLK high or low	3.3		3		2.8		2.5		ns	
t _{su}	Setup time, data before CLK ↑	3.5		2.5		2		1.5		ns	
t _h	Hold time, data after CLK ↑	3.4		1.6		1.5		1.5		ns	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM INPUT	TO (OUTPUT)	SN74LVC1G374 –40°C to 85°C								UNIT	
			V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f_{\max}			100		125		150		175		MHz	
t_{pd}	CLK	Q	2.5	15	2	6	1.4	4	1	3	ns	
t_{en}	\overline{OE}	Q	2.2	12	2	4.8	1.3	3.8	1.1	2.5	ns	
t_{dis}	\overline{OE}	Q	2.2	11	2	4.8	1.6	4.5	1.2	3.1	ns	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see [Figure 2](#))

PARAMETER	FROM INPUT	TO (OUTPUT)	SN74LVC1G374 –40°C to 85°C								UNIT	
			V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f_{\max}			100		125		150		175		MHz	
t_{pd}	CLK	Q	2.7	18.3	1.8	8.2	1.6	6	1	4	ns	
t_{en}	\overline{OE}	Q	2	13	1.5	6.3	0.9	5	0.7	3.5	ns	
t_{dis}	\overline{OE}	Q	2	14	1.1	5.3	1.4	4.5	0.8	3.1	ns	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see [Figure 2](#))

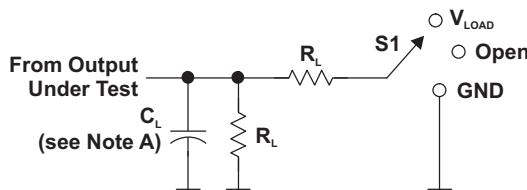
PARAMETER	FROM INPUT	TO (OUTPUT)	SN74LVC1G374 –40°C to 125°C								UNIT	
			V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f_{\max}			100		125		150		175		MHz	
t_{pd}	CLK	Q	2.7	18.3	1.8	10.2	1.6	7	1	5	ns	
t_{en}	\overline{OE}	Q	2	14	1.5	8.3	0.9	6.5	0.7	5.5	ns	
t_{dis}	\overline{OE}	Q	2	16	1.1	7.3	1.4	6	0.8	5.1	ns	

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	V _{CC} = 5 V TYP	UNIT	
						MIN	MAX
C_{pd} Power dissipation capacitance	Outputs enabled	$f = 10 \text{ MHz}$	24	24	25	27	pF
	Outputs disabled		8	8	9	11	

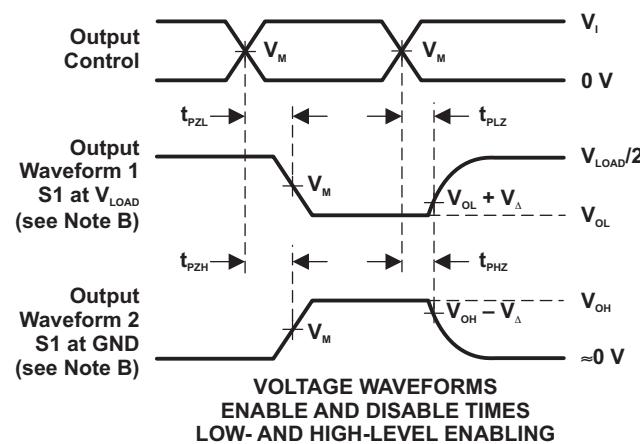
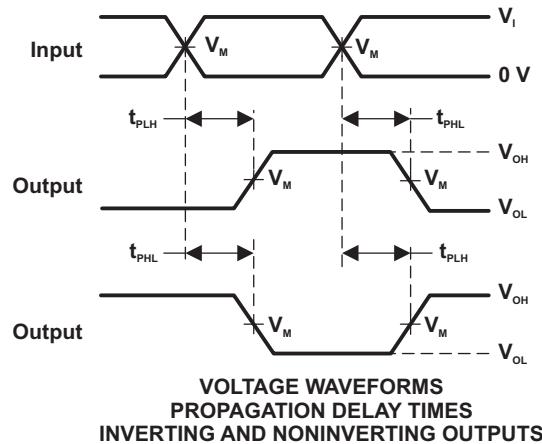
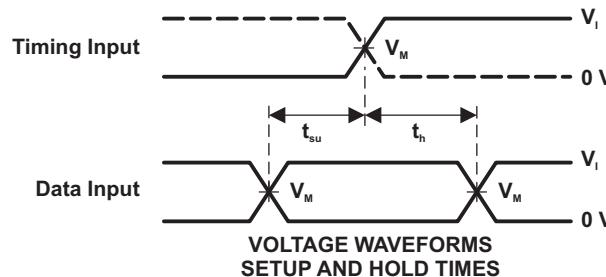
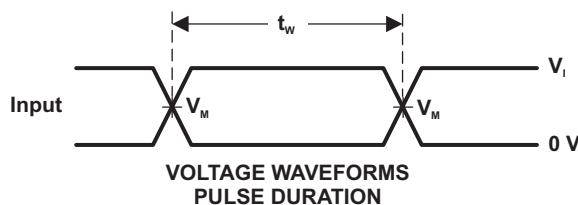
PARAMETER MEASUREMENT INFORMATION



TEST	S_1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

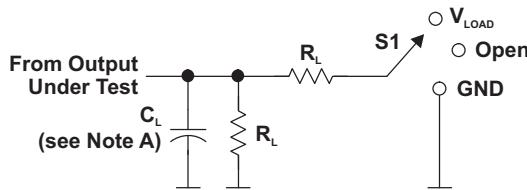
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
$1.8 \text{ V} \pm 0.15 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	$1 \text{ M}\Omega$	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.3 V



NOTES:

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_o = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

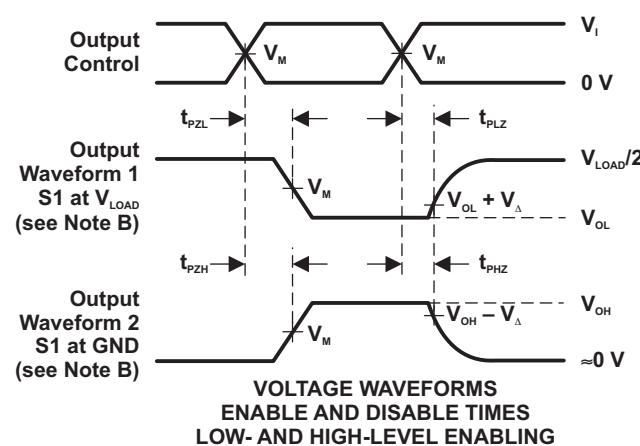
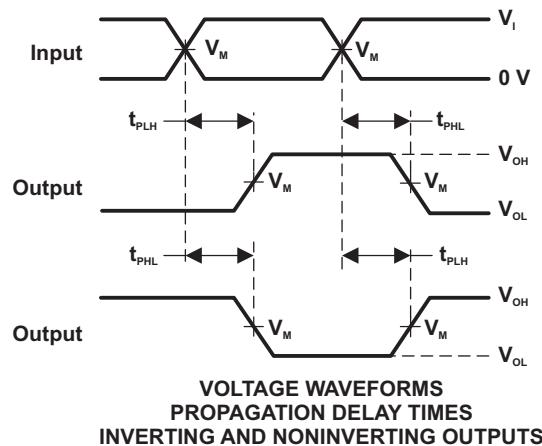
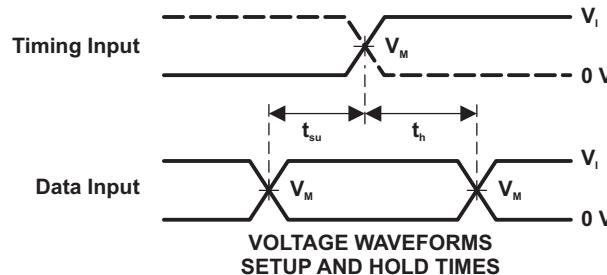
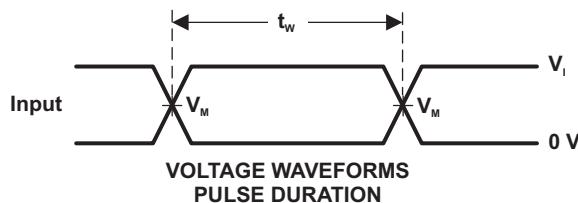
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_I/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	V_{CC}	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_o = 50\text{ }\Omega$.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en} .

G. t_{PLH} and t_{PHL} are the same as t_{pd} .

H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

REVISION HISTORY

Changes from Revision B (September 2006) to Revision C	Page
• Updated document to new TI data sheet format.	1
• Removed Ordering Information table.	2
• Added ESD warning.	2
• Updated operating temperature range.	3

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74LVC1G374DCKRG4	Active	Production	SC70 (DCK) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	D45
74LVC1G374DCKRG4.B	Active	Production	SC70 (DCK) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	D45
SN74LVC1G374DBVR	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(CA45, CA4R)
SN74LVC1G374DBVR.B	Active	Production	SOT-23 (DBV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(CA45, CA4R)
SN74LVC1G374DCKR	Active	Production	SC70 (DCK) 6	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(D45, D4J, D4R)
SN74LVC1G374DCKR.B	Active	Production	SC70 (DCK) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(D45, D4J, D4R)
SN74LVC1G374DCKRG4.B	Active	Production	SC70 (DCK) 6	3000 LARGE T&R	-	Call TI	Call TI	-40 to 125	
SN74LVC1G374YZPR	Active	Production	DSBGA (YZP) 6	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	D4N
SN74LVC1G374YZPR.B	Active	Production	DSBGA (YZP) 6	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	D4N

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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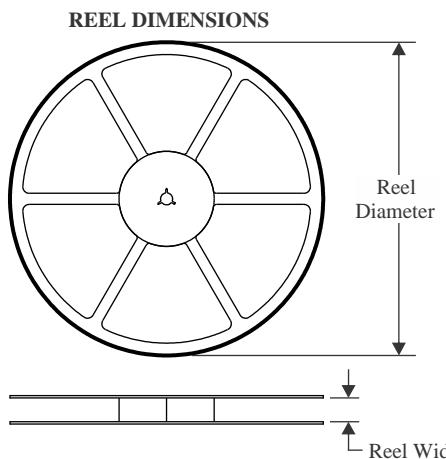
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OTHER QUALIFIED VERSIONS OF SN74LVC1G374 :

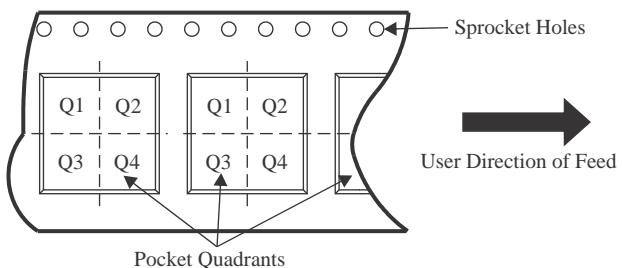
- Automotive : [SN74LVC1G374-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74LVC1G374DCKRG4	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G374DBVR	SOT-23	DBV	6	3000	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G374DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G374DCKR	SC70	DCK	6	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
SN74LVC1G374YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74LVC1G374DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74LVC1G374DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
SN74LVC1G374DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
SN74LVC1G374DCKR	SC70	DCK	6	3000	208.0	191.0	35.0
SN74LVC1G374YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0

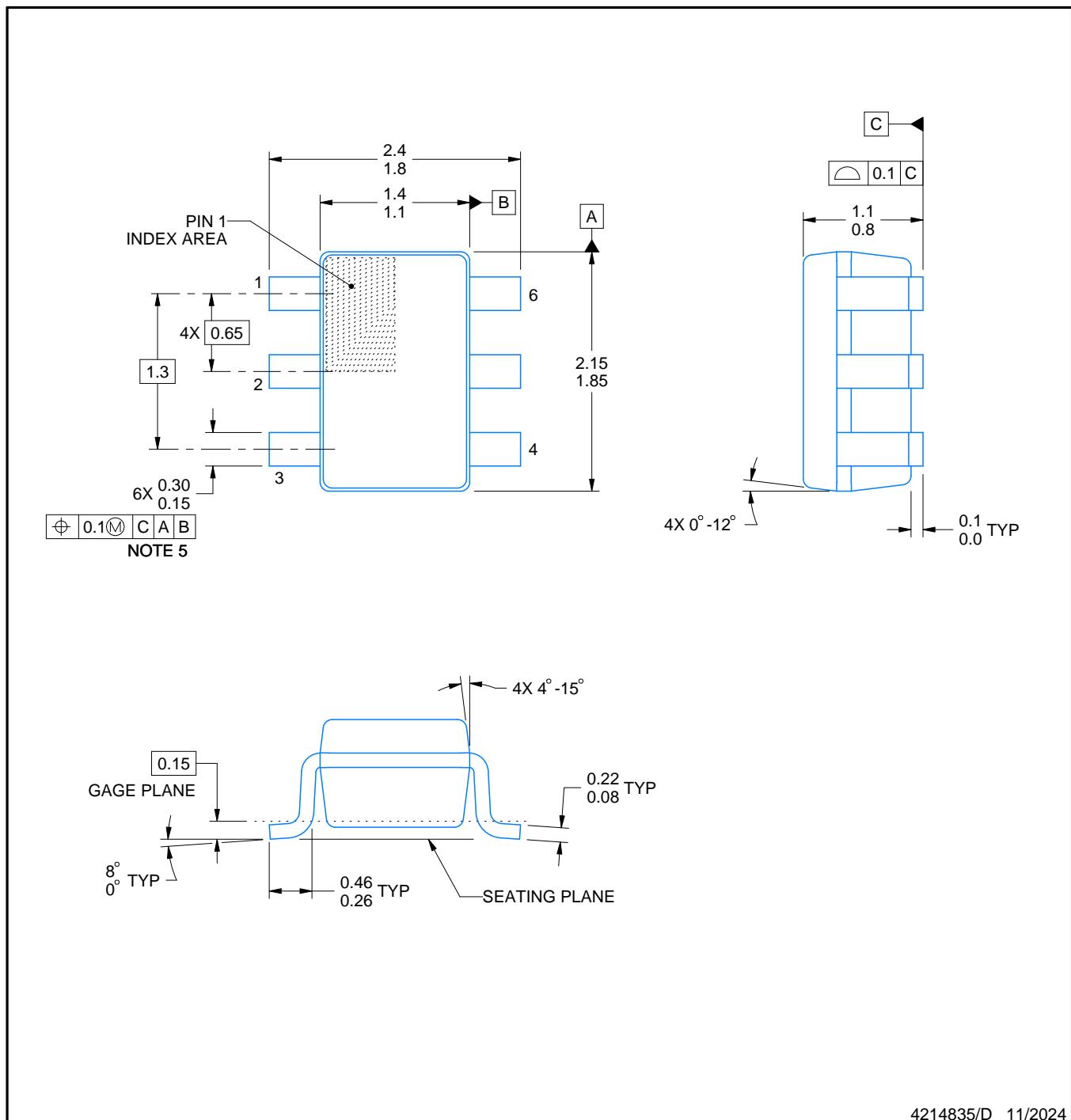
PACKAGE OUTLINE

DCK0006A



SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



NOTES:

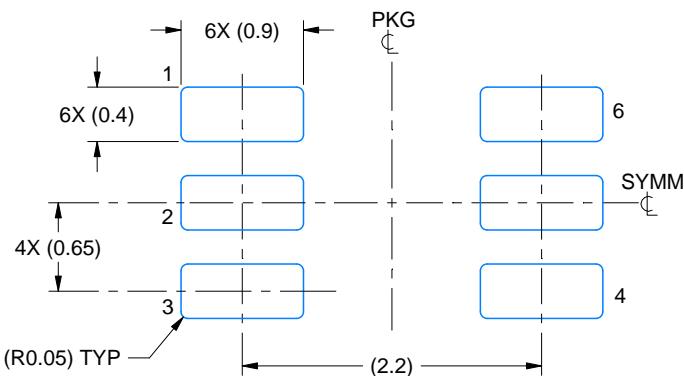
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Falls within JEDEC MO-203 variation AB.

EXAMPLE BOARD LAYOUT

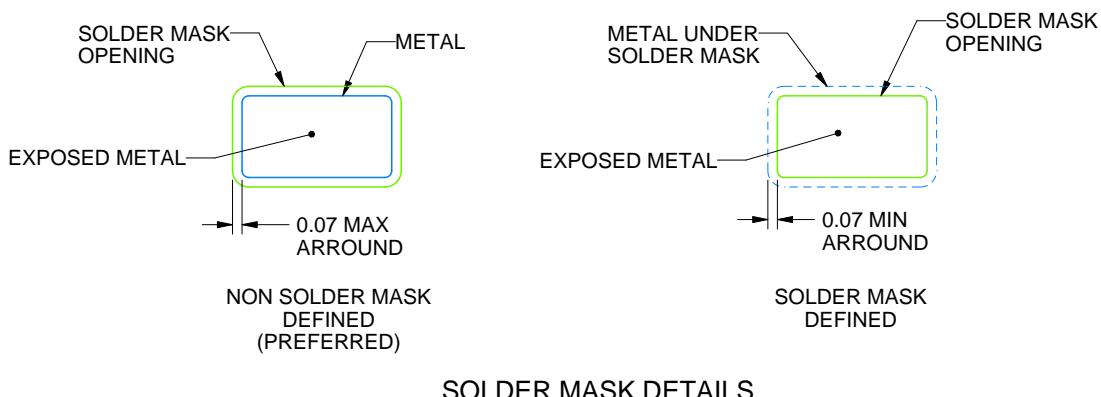
DCK0006A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



4214835/D 11/2024

NOTES: (continued)

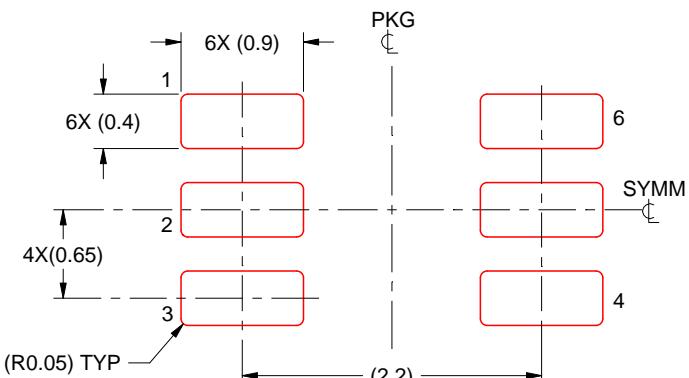
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCK0006A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

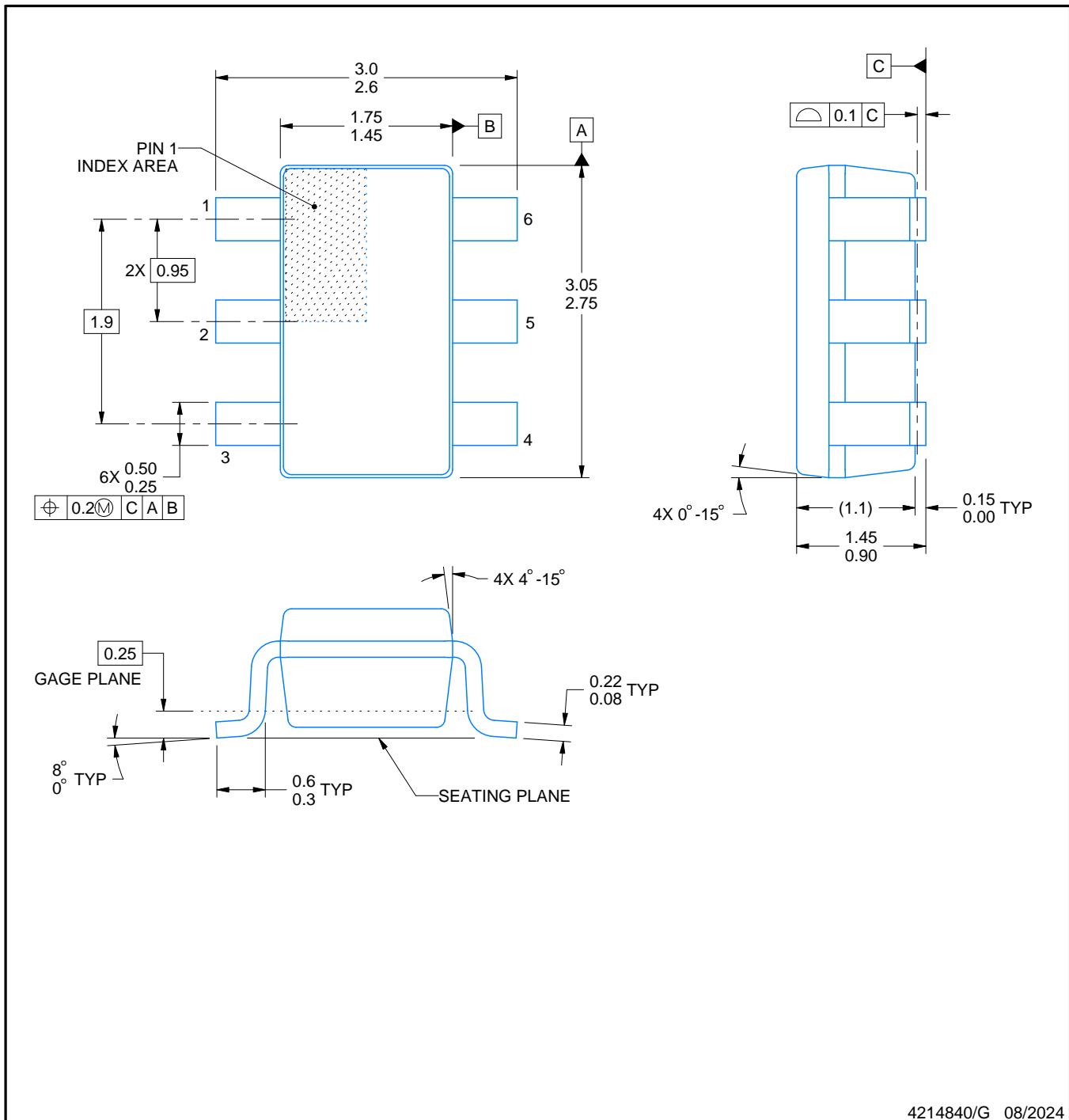
PACKAGE OUTLINE

DBV0006A



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



4214840/G 08/2024

NOTES:

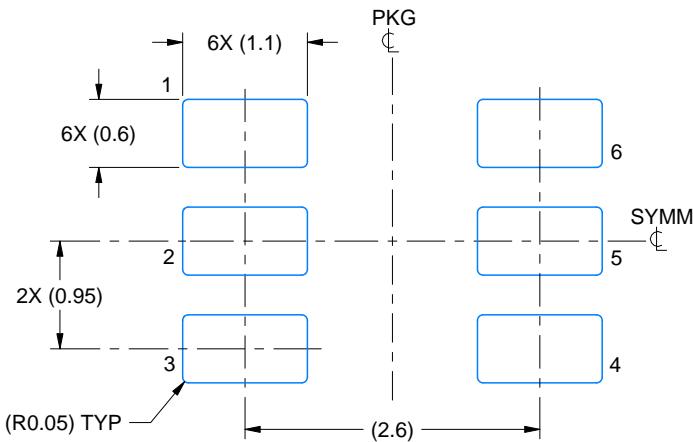
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Reference JEDEC MO-178.

EXAMPLE BOARD LAYOUT

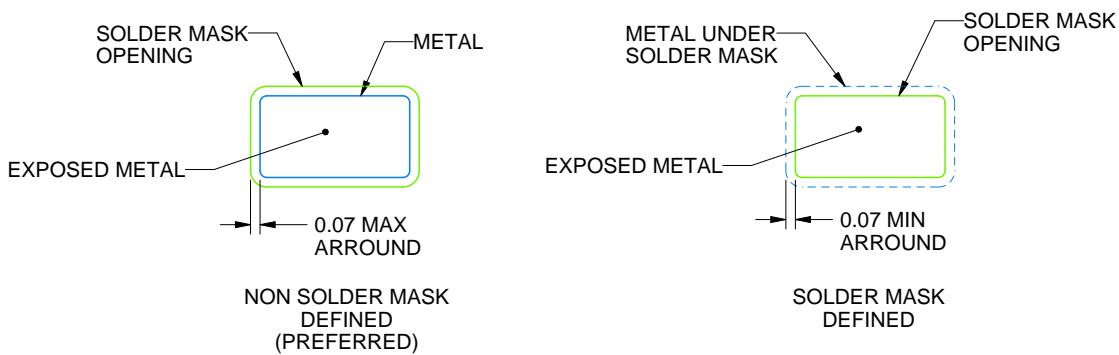
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

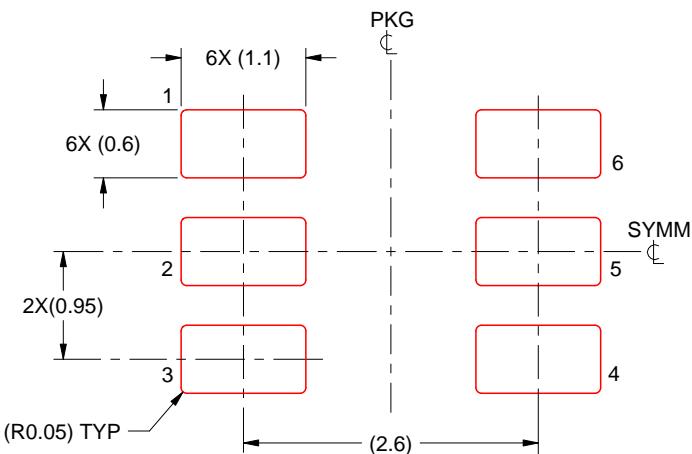
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR

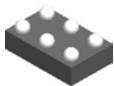


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

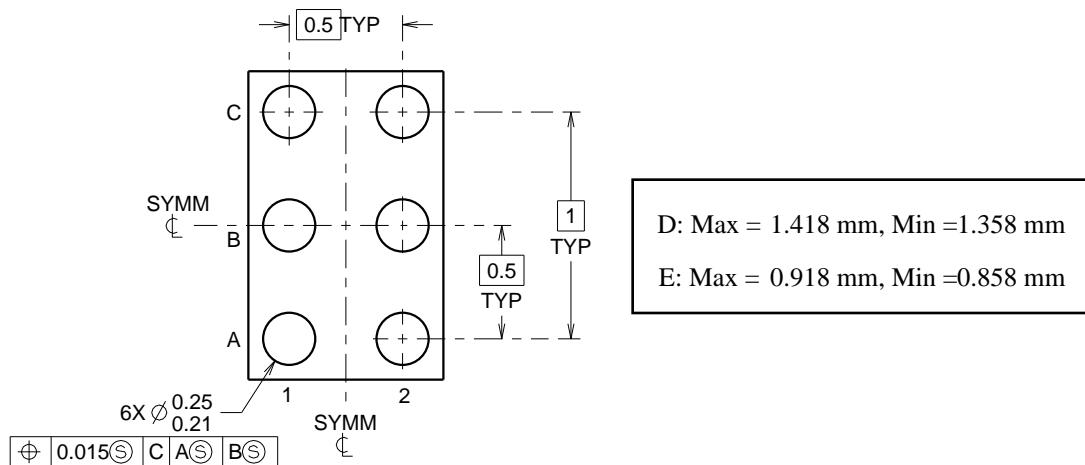
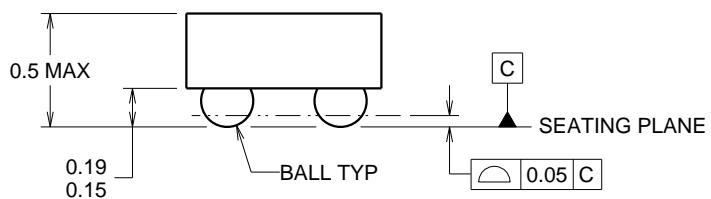
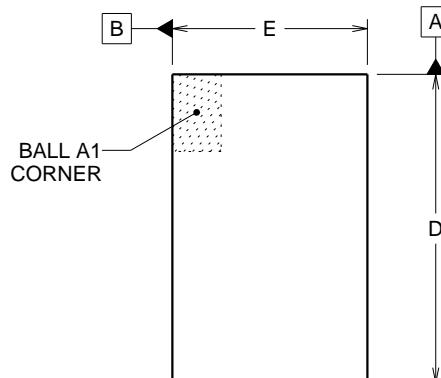


PACKAGE OUTLINE

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4219524/A 06/2014

NOTES:

NanoFree is a trademark of Texas Instruments.

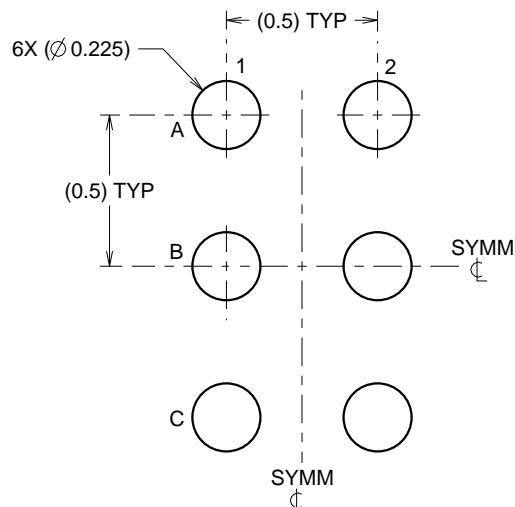
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.

EXAMPLE BOARD LAYOUT

YZP0006

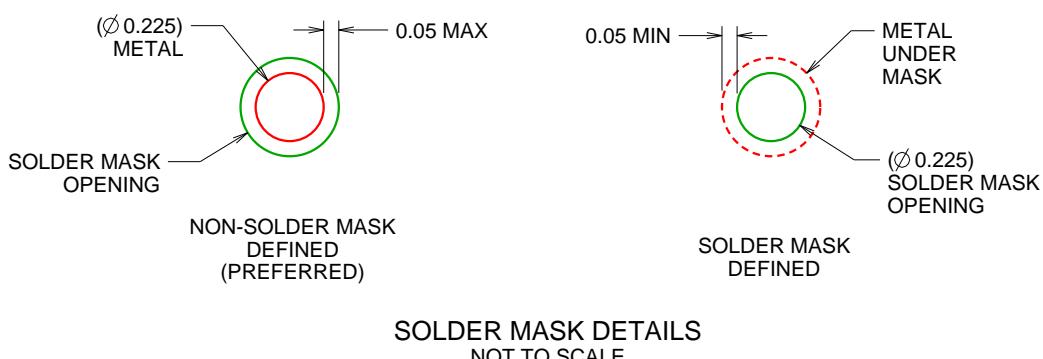
DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE

SCALE:40X



SOLDER MASK DETAILS
NOT TO SCALE

4219524/A 06/2014

NOTES: (continued)

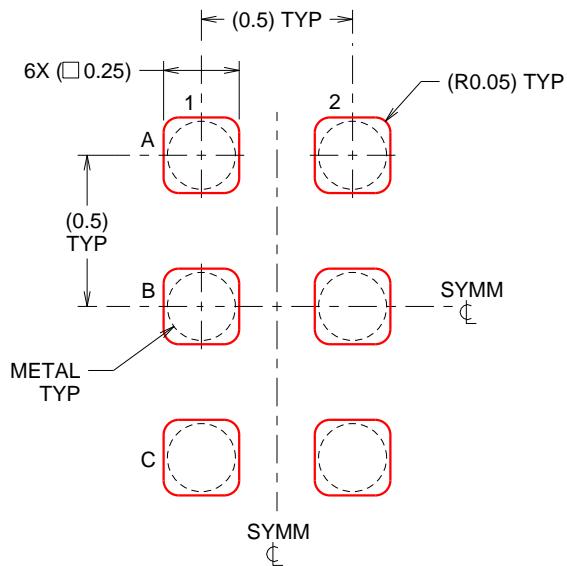
4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).

EXAMPLE STENCIL DESIGN

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219524/A 06/2014

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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